TOSHIBA

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RD Number: RD187 RD Title: TC78H670FTG Evaluation Circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	CN1	1	CN-2P	_	_	PCB terminal block 2 positions		
2	CN2	1	CN-2P	_	_	PCB terminal block 2 positions		
3	CN3	1	CN-2P	—	-	PCB terminal block 2 positions		
4	CVM1	1	47µF	_	-	Capacitor		
5	CVM2	1	0.1µF	—	-	Chip capacitor		
6	CEN	0	Not mount	—	-			✓
7	CVCC	1	0.1µF	—	-	Chip capacitor		
8	CVREF	1	0.1µF	—	-	Chip capacitor		
9	R1	0	Not mount	_	-			1
10	R2	0	Not mount	—	-			1
11	R3	1	10kΩ	_	-	Chip resistor		
12	R4	1	10kΩ	—	-	Chip resistor		
13	R5	1	10kΩ	—	-	Chip resistor		
14	R6	1	10kΩ	_	-	Chip resistor		
15	R7	1	10kΩ	—	-	Chip resistor		
16	R8	1	10kΩ	_	-	Chip resistor		
17	R9	1	10kΩ	—	-	Chip resistor		
18	R10	1	10kΩ	—	-	Chip resistor		
19	R11	0	Not mount	—	-			1
20	R12	0	Not mount	—	-			1
	R13	0	Not mount	—	-			✓
22	R14	0	Not mount	—	-			1
23	REN	1	10kΩ	—	-	Chip resistor		
24	ROSC	1	47kΩ	—	-	Chip resistor		
25	VR1	0	Not mount	—	—	Variable Resistor		✓
26	U1	1	TC78H670FTG	TC78H670FTG	TOSHIBA	Stepping Motor Driver IC	QFN16	
27	SW0	0	Not mount	—	-	Toggle switch		1
	SW1	0	Not mount	_	-	Toggle switch		1
29	SW2	0	Not mount	_	—	Toggle switch		1
30	SW3	0	Not mount	_	—	Toggle switch		1
31	AGND	0	Not mount	_	-	Check terminal		1
32	EN	0	Not mount	—	—	Check terminal		✓
33	ERR	0	Not mount	_	_	Check terminal		1

34	MODE0	0	Not mount		_	Check terminal	1
35	MODE1	0	Not mount	—	_	Check terminal	✓ ✓
36	MODE2	0	Not mount	_	—	Check terminal	✓ ✓
37	MODE3	0	Not mount	—	_	Check terminal	✓ ✓
38	OSCM	0	Not mount	—	—	Check terminal	✓ <i>✓</i>
39	OUT_A+	0	Not mount	_	—	Check terminal	✓ <i>✓</i>
40	OUT_A-	0	Not mount	—	—	Check terminal	✓ <i>✓</i>
41	OUT_B+	0	Not mount	_	—	Check terminal	✓ ✓
42	OUT_B-	0	Not mount	—	—	Check terminal	✓ <i>✓</i>
43	PGNDA	0	Not mount	—	—	Check terminal	✓ <i>✓</i>
44	PGNDB	0	Not mount	_	—	Check terminal	✓ ✓
45	STBY	0	Not mount	—	—	Check terminal	✓ <i>✓</i>
46	TP3	0	Not mount	_	—	Check terminal	✓ ✓
47	VM	0	Not mount	—	—	Check terminal	✓ <i>✓</i>
48	VREF	0	Not mount	—	—	Check terminal	✓ ✓
49							
50							

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